

SESSION 2: RF MODULES

Chair: Yohei Otoki, *Hitachi Cable, Ltd.* and Earl Lum, *EJL Wireless*

Today we are living in the wireless world, which is filled with an ever expanding variety of cell phones, W-LANs, WWANs, GPS, and a host of other wireless appliances. The application of these RF technologies continues spreading into new systems like smart grid and e-book and even into entertainment systems and toys. At the core of these wireless systems are RF modules which are powered and enabled primarily by Compound Semiconductor devices and packaged components and subassemblies of these. This special session will provide an up to date overview of the RF module manufacturing technology, as well as prospects for future directions for this industry. The session begins with an invited presentation by Mr. Ando from Navian who will provide a business overview and a description of the technical status and trends in the manufacture of RF modules. Next, we will have a panel session with panelists who are expert RF module engineers from Murata, AVAGO, TDK, Skyworks, RFMD and TriQuint. The panelists will give an overview of their products and describe some of the technical activities and challenges at their companies. They will describe what they expect and require from materials, at the device level, from the IC components, and from their packaging technologies. A lively and enlightening discussion is to be expected at in the question and answer period following the panel presentations.